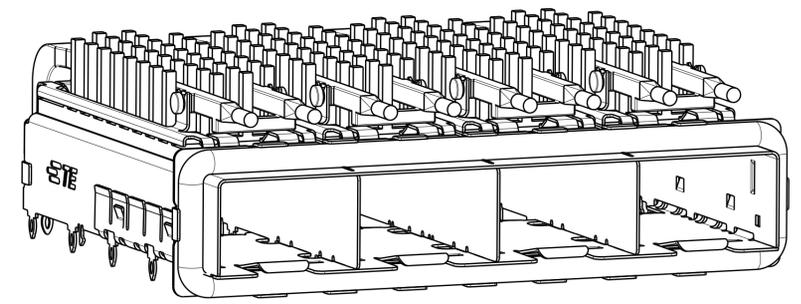


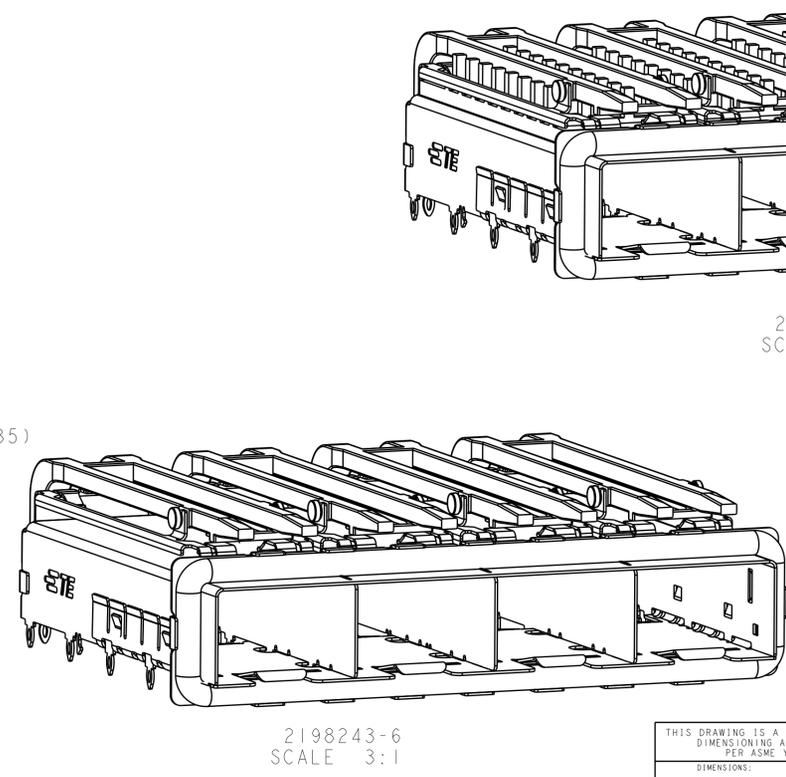
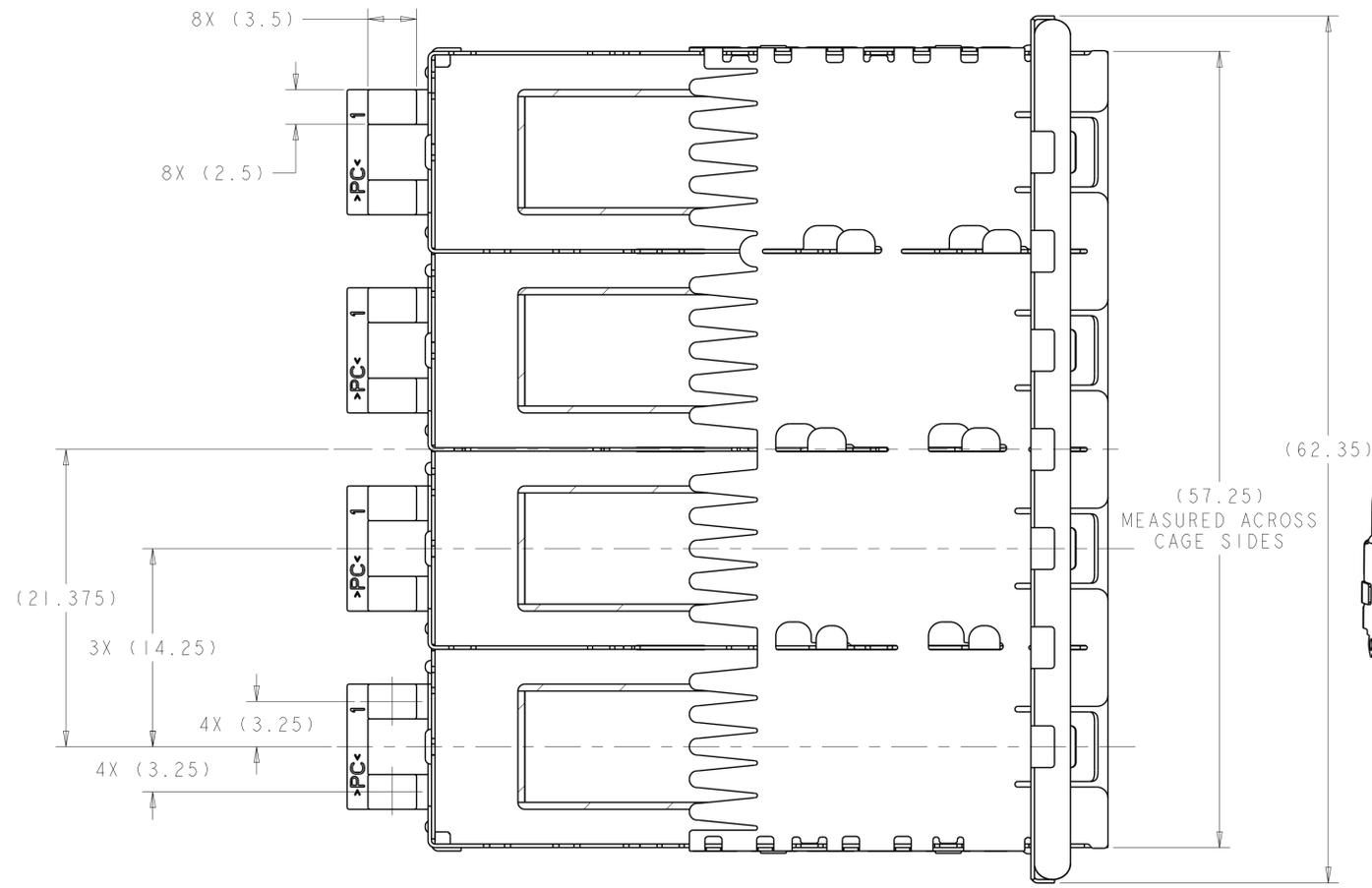
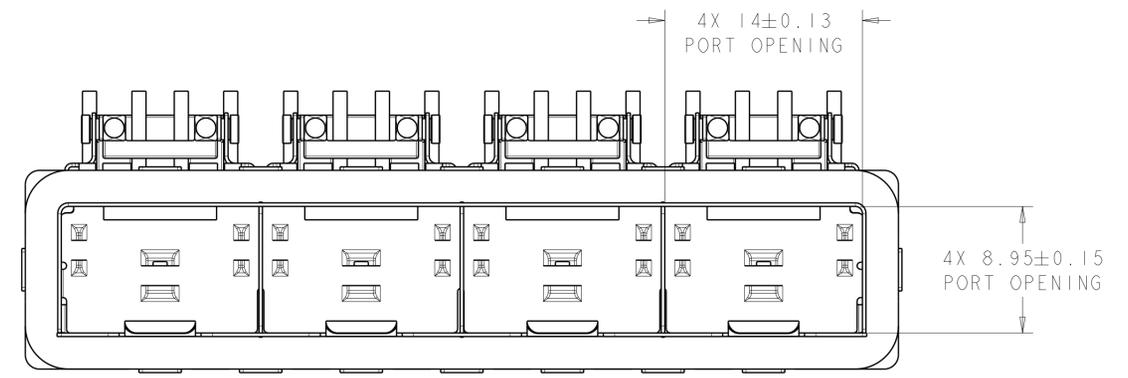
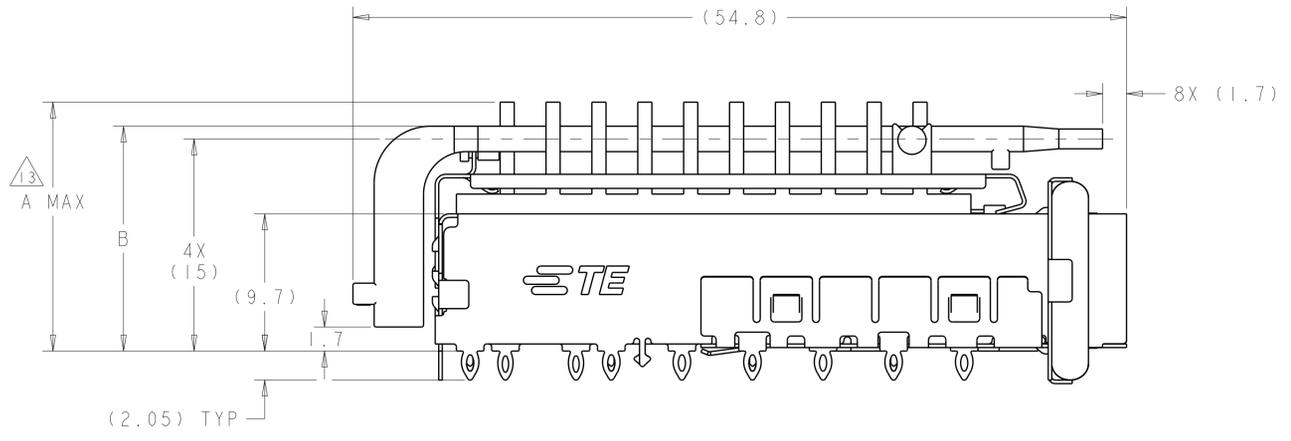
LOC	DIST	REVISIONS					
GP	00	P	LTN	DESCRIPTION	DATE	DWN	APVD
		B		REVISED PER ECO-13-003777	18MAR2013	CJV	MRS
		B1		ADD 2198243-5	4JUN2015	RG	SH
		B2		UPDATE TOTAL HEIGHT OF -5	9JUN2015	RG	SH
		B3		REVISED PER ECO-15-009468	17JUN2015	RG	SH



2198243-3
 FINISHED ASSEMBLY
 SCALE 3:1

- 1 MATERIAL:
 CAGE ASSEMBLY: 0.25mm THICK NICKEL SILVER ALLOY
 GASKET RETENTION PLATE: STAINLESS STEEL
 EMI GASKET: PLATED FILLED SILICONE
 HEATSINK/LIGHTPIPE CLIP: STAINLESS STEEL
 HEATSINK: ALUMINUM
 LIGHTPIPE: POLYCARBONATE, CLEAR
- 2 FINISH:
 HEATSINK: ELECTROLEISS NICKEL
 HEATSINK/LIGHTPIPE CLIP: PASSIVATE
- 3 PADS AND VIAS CHASSIS GROUND.
- 4 DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.
- 5 MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.
- 6 INTERPRETATION OF DATUM REFERENCE FRAME IN ACCORDANCE WITH SECT 4.4.1.1 OF ASME Y14.5M-1994.
- 7 REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- 8 REFERENCE APPLICATION SPEC. 114-13120, HOLE B, FOR RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- 9 HOLE PATTERN REPEATS FOR EACH PORT. SPACING BETWEEN PORTS IS 14.25mm.

- 10 MINIMUM PC BOARD THICKNESS:
 SINGLE SIDED: 1.5mm
- 11 CERTAIN MATING TRANCEIVERS MAY REQUIRE ADDITIONAL PCB THICKNESS THAT WOULD NEED TO BE DETERMINED BY THE CUSTOMER.
- 12 PRODUCT COMPLIES WITH SPECIFICATION SFF-8433 IMPROVED PLUGGABLE FORM FACTOR FOR SFP+ GANGED CAGES.
- 13 DIMENSION APPLIES PRIOR TO INSERTION OF SFP MODULE.
- 14 HEATSINK, HEATSINK CLIP, AND LIGHTPIPE SHIPPED UNASSEMBLED TO CAGE ASSEMBLY. CAGE ASSEMBLY TO BE PRESSED INTO PCB PRIOR TO ATTACHING HEATSINK, HEATSINK CLIP, AND LIGHTPIPE TO THE CAGE ASSEMBLY.
- 15 PACKAGED AS A COMPLETE ASSEMBLY.



2198243-6
 SCALE 3:1

B	A MAX	APPLICATION	PART NUMBER
15.3	N/A	NO HEAT SINK	2198243-6
15.3	14.9	SAN	2198243-5
15.9	22.5	NETWORKING, TALL	2198243-4
15.9	18.1	NETWORKING, SHORT	2198243-3
15.9	15.5	SAN	2198243-2
15.9	13.2	PCI	2198243-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009. TOLERANCES UNLESS OTHERWISE SPECIFIED:

DIMENSIONS:	mm	0 PLC ±0.1	1 PLC ±0.1	2 PLC ±0.1	3 PLC ±0.1	4 PLC ±0.1	ANGLES ±0.1	FINISH ±1°
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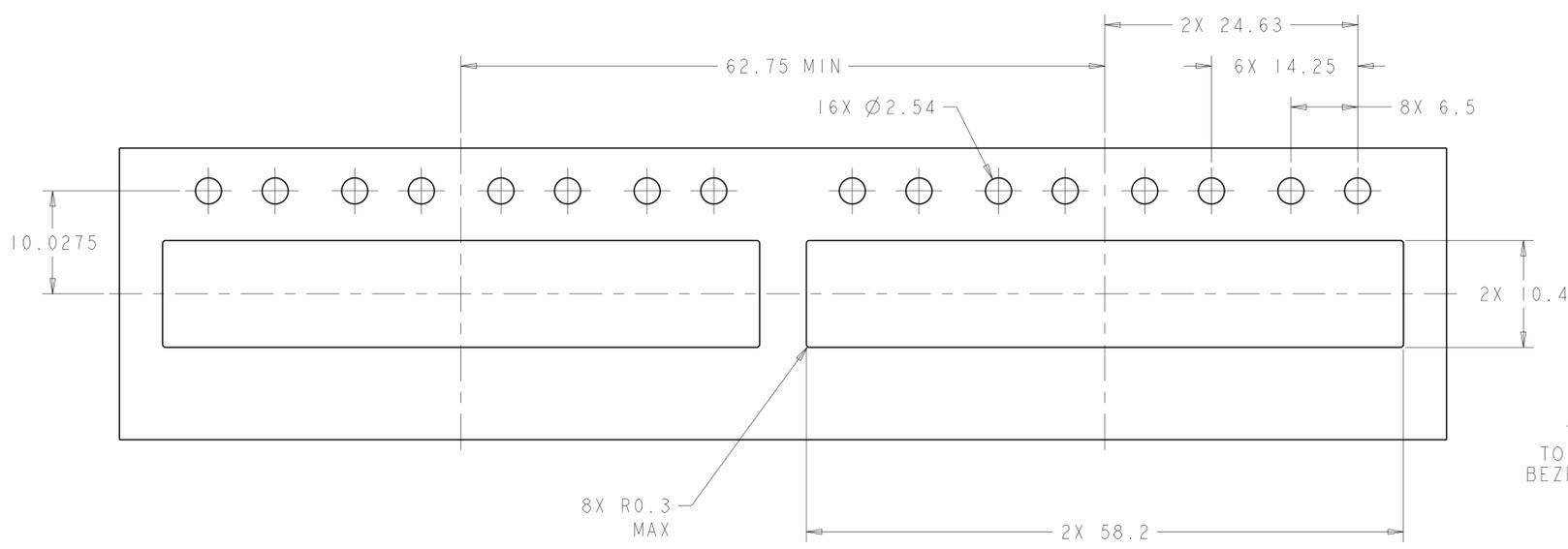
MATERIAL: FINISH:

DWN	B. MATTHEWS	20OCT2011
CHK	M. SCHMITT	20OCT2011
APVD	M. SCHMITT	20OCT2011

PRODUCT SPEC: 108-2364
 APPLICATION SPEC: 114-13120
 WEIGHT: -

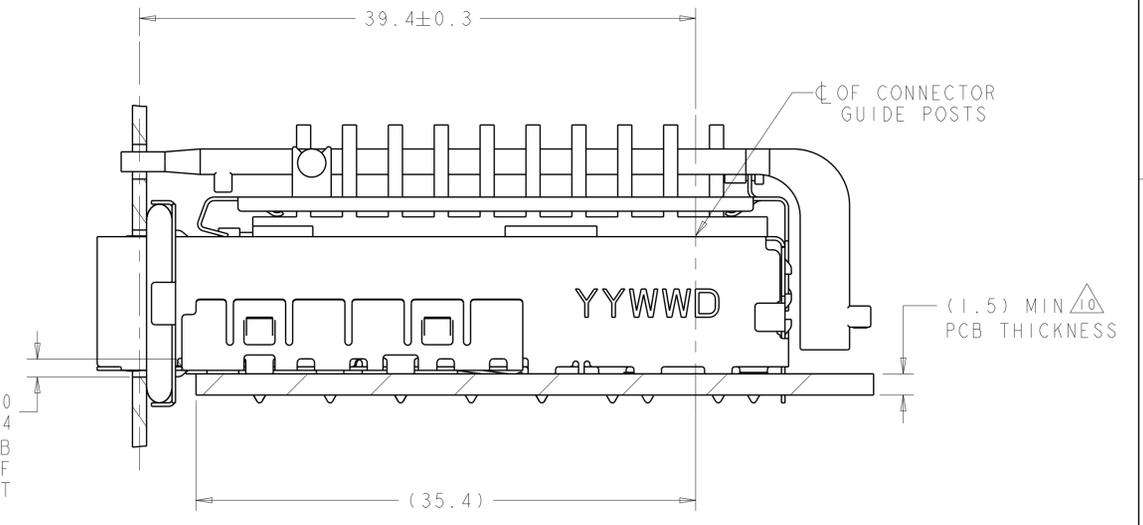
Customer Drawing SCALE 4:1 SHEET 1 OF 4 REV B3

LOC	DIST	REVISIONS			
P	LTN	DESCRIPTION	DATE	DMN	APVD
-	-	SEE SHEET 1	-	-	-

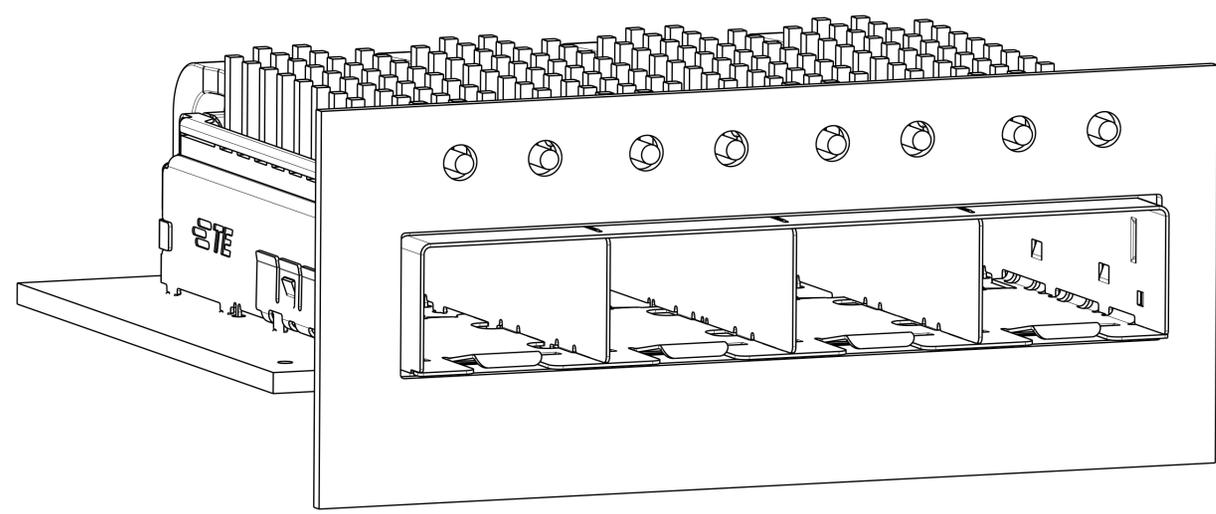


RECOMMENDED BEZEL CUT-OUT
 SINGLE SIDED APPLICATIONS
 SCALE 3:1

0.23^{+0.10}_{-0.14}
 TOP OF PCB
 TO INSIDE OF
 BEZEL CUT-OUT



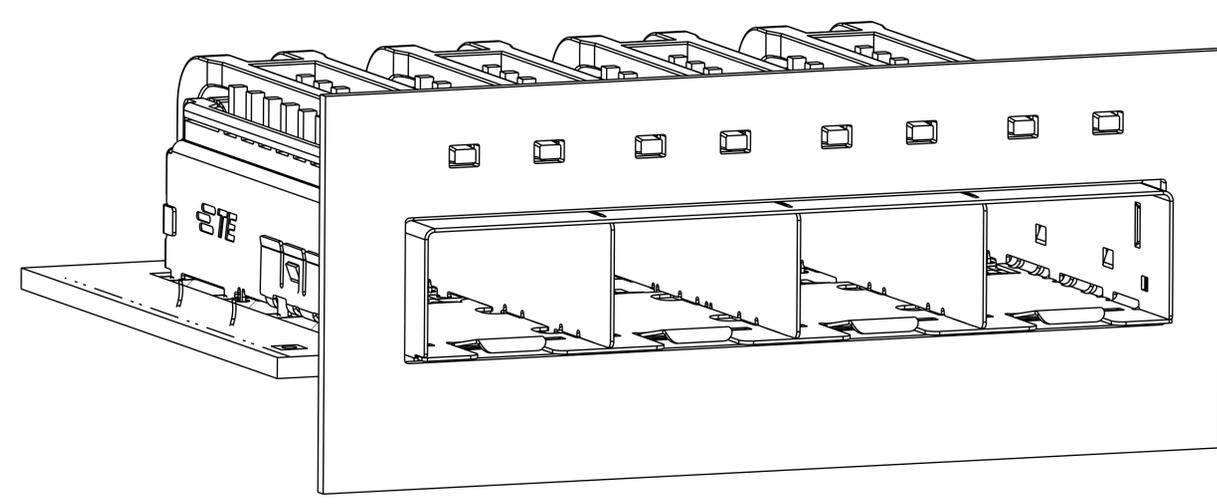
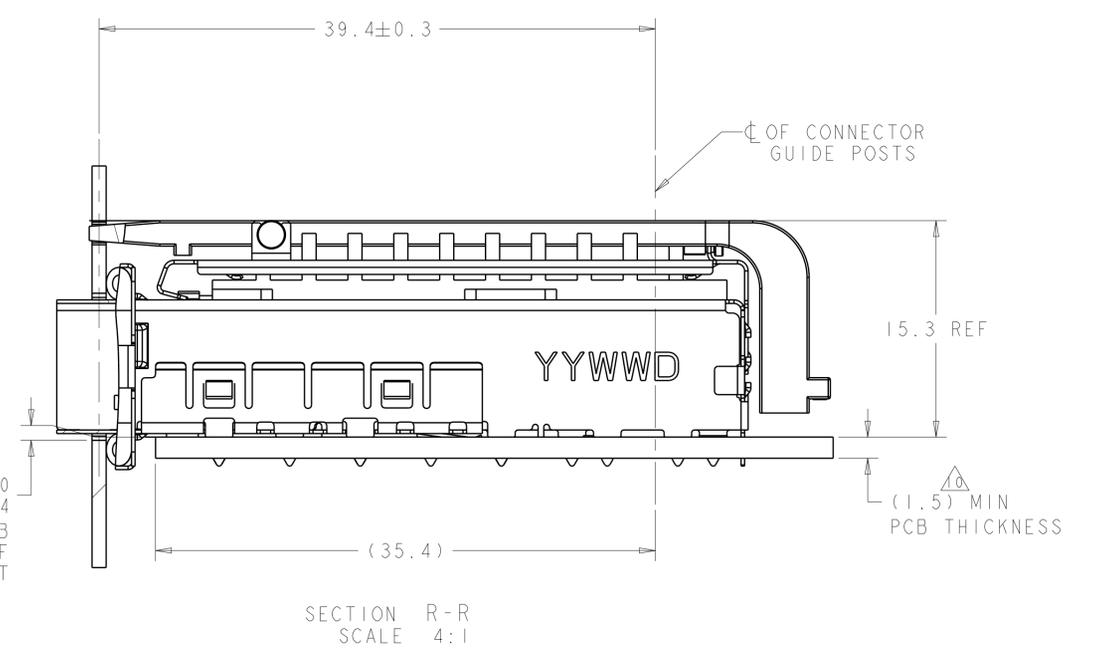
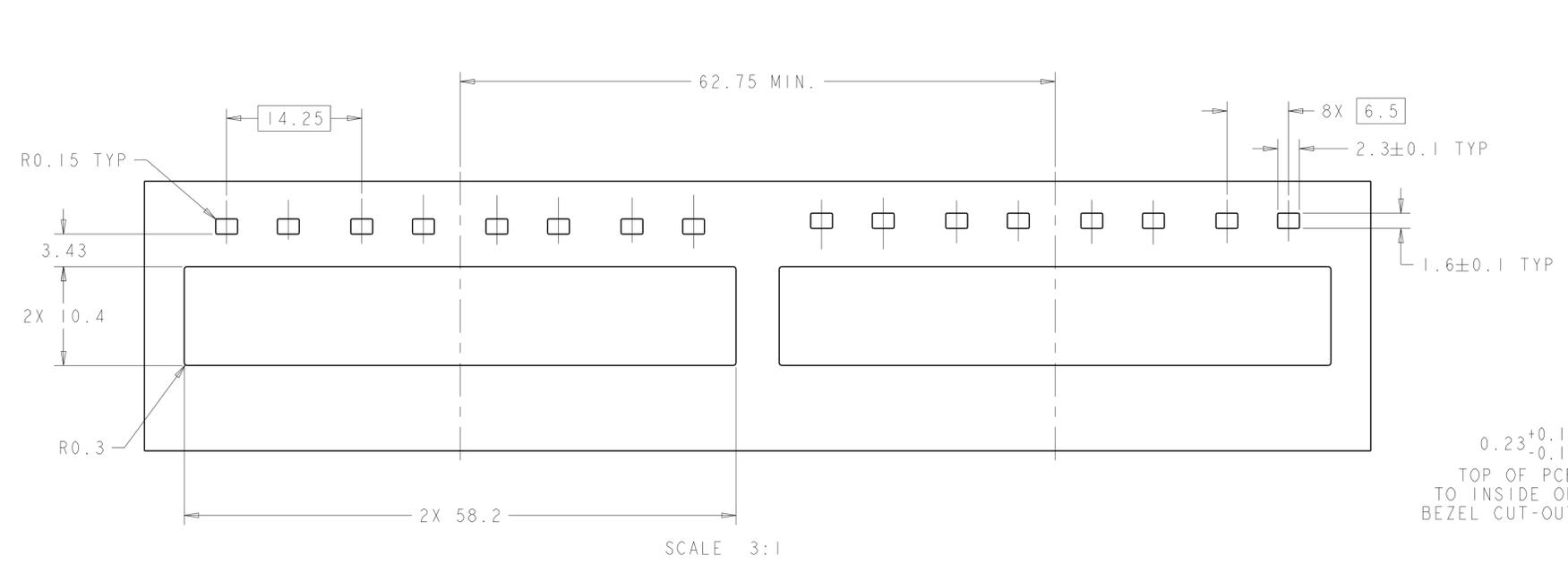
2198243
 MOUNTED ON PCB
 SHOWN THRU RECOMMENDED BEZEL



2198243
 MOUNTED ON PCB
 SHOWN THRU RECOMMENDED BEZEL

THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009		DMN: B. MATTHEWS 20OCT2011 CHK: M. SCHMITT 20OCT2011 APVD: M. SCHMITT 20OCT2011	TE Connectivity STE	
DIMENSIONS: mm TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ±0.1 1 PLC ±0.1 2 PLC ±0.1 3 PLC ±0.1 4 PLC ±0.1 ANGLES ±1° FINISH		NAME: SFP+ ENHANCED 1X4 CAGE ASSEMBLY, PRESS FIT, EMI GASKET WITH HEATSINK AND LIGHTPIPE PRODUCT SPEC: 108-2364 APPLICATION SPEC: 114-13120 WEIGHT: - Customer Drawing		

LOC	DIST	REVISIONS			
GP	00	REV	DATE	BY	APPV
-	-	SEE SHEET 1	-	-	-



2198243-5
 MOUNTED ON PCB
 SHOWN THRU RECOMMENDED BEZEL
 SCALE 4:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN B. MATTHEWS 20OCT2011 CHK M. SCHMITT 20OCT2011 APVD M. SCHMITT 20OCT2011	TE Connectivity
DIMENSIONS: mm 	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ±0.1 1 PLC ±0.1 2 PLC ±0.1 3 PLC ±0.1 4 PLC ±0.1 ANGLES ±1°	NAME SFP+ ENHANCED 1X4 CAGE ASSEMBLY, PRESS FIT, EMI GASKET WITH HEATSINK AND LIGHTPIPE PRODUCT SPEC 108-2364 APPLICATION SPEC 114-13120 WEIGHT - Customer Drawing	

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<http://moschip.ru/get-element>

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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